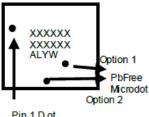


Title of Change:	Transfer of the Manufacturing of QFN20 4X4 Assembly Devices from SPEL Semiconductor Limit to Limited Site 3 for Wireless Connectivity Solutions Products.					
Proposed first ship date:	20 October 2018 or earlier after customer approval.					
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>peter.vo@onsemi.com</u> >					
Samples:	Contact your local ON Semiconductor Sales Office or < <u>PCN.samples@onsemi.com</u> > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.					
Additional Reliability Data:	Contact your local ON Semiconducto	or Sales Office or < <u>Phine.Guevarra@onsemi.com</u> >.				
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < <u>PCN.Support@onsemi.com></u>					
Change Part Identification:	Affected parts are marked with the	manufacturing site code, "G", for UTAC Thai Limited.				
Change Category:	🔽 Wafer Fab Change 🔽 Ass	embly Change 🔲 Test Change 🔲 Other				
Change Sub-Category(s): Manufacturing Site Add Manufacturing Site Tran Manufacturing Process 	isfer Product specific ch	 □ Datasheet/Product Doc change □ Shipping/Packaging/Marking □ Other: 				
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: UTAC				

Description and Purpose:

This final product change notification is to inform the assembly manufacturing transfer of the affected parts of package type QFN20 4X4 for Wireless Connectivity Solutions products from SPEL Semiconductor Limit to UTAC Thai Limited Site 3. This change is to allow better management of the supply chain to meet customers' demands. With the transfer, the BOM is changing from SPEL to UTAC, and the BOM at UTAC are standard material. The package case outline is not affected by this change. The product marking will change to be compliant to ON Semiconductor's marking specification as illustrated below.



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	Marking Change	Before Chang	e Description	After Change Description			
		Assembly	Site: SPEL	Assembly Site: UTAC Thai Limited Site 3			
	Part Number	Line 1 Marking	Line 2 Marking	Line 1 Marking	Line 2 Marking	Line 3 Marking	
	AX5031-1-TA05	AX5031-1	Trace Code	AX5031	-1	Trace Code	
	AX5031-1-TW30	AX5031-1	Trace Code	AX5031	-1	Trace Code	
ĺ	AX5243-1-TA05	AX5243-1	Trace Code	AX5243	-1	Trace Code	
	AX5243-1-TW30	AX5243-1	Trace Code	AX5243	-1	Trace Code	



	Material Ch	ange	Before	Change Descrip	otion	After C	hange Descri	ption
	Site			SPEL		UTAC	C Thailand Sit	e 3
	Leadframe		Cu		PPF			
	Epoxy Wire		CRM-1076NS		8600			
			0.8MIL Au			0.7MIL Au		
	Mold			G770HCD			G700LTD	
	Finish Plat	ting		Tin			NiPdAu	
	arity on below do	e vice previously c X8052F143-3-TX3 FN 407X5	-	at UTAC Thailan	d.			
	Test	Specificatio	on	(Condition		Interval	Results
	HTSL	JESD22-A10	03	г	Ta= 150°C		1008 hrs	0/240
	HTSL TC	JESD22-A10 JESD22-A10			Ta= 150°C 65°C to +150°C	:	1008 hrs 500 cyc	0/240 0/240
			04	Ta=-6				
	тс	JESD22-A10	04 18	Ta= -6 130°C, 85% R	65°C to +150°C		500 сус	0/240
	TC uHAST	JESD22-A10 JESD22-A1	04 18 0-A113	Ta= -6 130°C, 85% R MSI	65°C to +150°C RH, 18.8psig, ur		500 сус	0/240 0/240
	TC uHAST PC	JESD22-A10 JESD22-A11 J-STD-020 JESD	04 18 0-A113 06	Ta= -6 130°C, 85% R MSI Ta =	65°C to +150°C RH, 18.8psig, ur L 1 @ 260 °C		500 сус	0/240 0/240 0/480
	TC UHAST PC RSH SD	JESD22-A10 JESD22-A11 J-STD-020 JESD JESD22- B1 JSTD002	04 18 0-A113 06	Ta= -6 130°C, 85% R MSI Ta =	65°C to +150°C RH, 18.8psig, ur L 1 @ 260°C 265C, 10 sec		500 сус	0/240 0/240 0/480 0/30
lectrical charact	TC UHAST PC RSH SD acteristic Summ teristics are not i Parts:	JESD22-A10 JESD22-A11 J-STD-020 JESD JESD22- B1 JSTD002 mary:	04 18 0-A113 06	Ta= -6 130°C, 85% R MSI Ta =	65°C to +150°C RH, 18.8psig, ur L 1 @ 260°C 265C, 10 sec	nbiased	500 сус	0/240 0/240 0/480 0/30 0/45
lectrical charact	TC UHAST PC RSH SD Acteristic Summer teristics are not in Parts: Part	JESD22-A10 JESD22-A11 J-STD-020 JESD JESD22- B1 JSTD002 mary: mpacted by this c	04 18 0-A113 06	Ta= -6 130°C, 85% R MSI Ta =	65°C to +150°C RH, 18.8psig, ur L 1 @ 260°C 265C, 10 sec	nbiased	500 cyc 96 hrs	0/240 0/240 0/480 0/30 0/45
lectrical charact	TC UHAST PC RSH SD Acteristic Summer teristics are not in Parts: Part AX503	JESD22-A10 JESD22-A11 J-STD-020 JESD JESD22- B1 JSTD002 mary: mpacted by this o	04 18 0-A113 06	Ta= -6 130°C, 85% R MSI Ta =	65°C to +150°C RH, 18.8psig, ur L 1 @ 260°C 265C, 10 sec	nbiased Qu	500 cyc 96 hrs	0/240 0/240 0/480 0/30 0/45

"Please be informed that there may be Customer Specific part/s impacted by this Notification, thus MPN & CPN info will not be reflected in the parts list of this Generic document. Instead please click the link to the addendum PCN copy provided in the email notification to see full list of affected products specific to your company."



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Product	Customer Part Number	Qualification Vehicle	
AX5031-1-TA05		AX8052F143-3-TX30	
AX5031-1-TW30		AX8052F143-3-TX30	
AX5243-1-TA05		AX8052F143-3-TX30	
AX5243-1-TW30		AX8052F143-3-TX30	